AMD EPYC SP6 CPU Liquid Cold Plate

Model T-HS202319 · AMD CPU · 300 W · Copper, TLP

Rated heat load	Max. surface temp.	Flow / pressure drop	Total height
300 W	**<55°C**	**3.3 LPM / 3 kPa**	**16 mm**



T-HS202319

16 mm low-profile cold plate for AMD EPYC 8004 (SP6, LGA4844) Siena processors. Wide, low-restriction channels: 300 W below 55 °C at 40 °C inlet (15 K rise, ≈ 0.050 °C/W) with 3 kPa at 3.3 LPM. Designed for high-flow / low-head loops typical of telecom and edge enclosures with 40% EGW.

Performance & mechanical data

Parameter	Value
Rated heat load	300 W
Coolant (as tested)	40% EG / water (EGW)
Inlet coolant temperature	40 °C
Max. plate surface temperature	< 55 °C
Flow rate / pressure drop	3.3 LPM / 3 kPa
Working pressure rating	1 MPa
Dimensions (L × W × H)	120 × 79 × 16 mm

Case-to-inlet thermal resistance: **≈ 0.0500 °C/W (from rated point)**

Construction

Parameter	Value
Base material	Copper
Bonding process	TLP — Transient Liquid-Phase Diffusion Bonding
Working pressure rating	1 MPa
Coolant compatibility	Water / EGW / PGW mixtures (validated as listed)
Fittings & port position	Per drawing; customisable on request
Leak test	100% pressure-tested before shipment

Typical applications

- AMD EPYC Siena edge and telecom servers
- Energy-efficient cloud nodes
- Space-constrained 1U chassis

Ordering & RFQ

How to order: quote model T-HS202319 with quantity and required fitting type.

RFQ checklist: target device / PCB, quantity, coolant type, inlet temperature, target flow rate, mechanical envelope.

Contact: www.tonecooling.com · sales@tonecooling.com

Performance values are typical results at the stated coolant, inlet temperature and flow rate; surface temperature is measured at the device contact area. TIM and mounting pressure affect final junction temperature. Specifications subject to change without notice. Third-party product names are trademarks of their respective owners and are used for compatibility reference only. © 2026 ToneCooling Technology Co., Ltd.